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umicore Electroplating

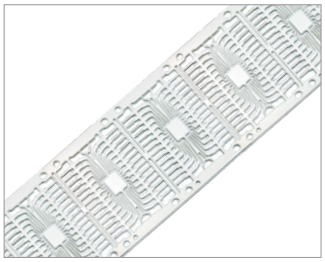
ARGUNA® ET-S

FINE SILVER ELECTROLYTE

High-Speed Electrolyte for Continuous Lines

The ARGUNA® ET-S silver electrolyte is an alkaline-cyanide process specifically developed for use in high-speed equipment for reel-to-reel silver plating (using flow or spray technologies). The process deposits smooth and fine-grained, semi-bright coatings which are particularly suitable for semiconductor technology.

Current density and plating speed depend on the electrolyte agitation at the parts, i.e. on the equipment used. High flow velocities allow very high current densities.



Advantages

- High-speed electrolyte for all-over and selective deposition of fine silver
- For continuous lines using flow or spray technologies
- Semi-bright coatings with very good soldering and bonding properties
- Use of soluble anodes possible

Applications

- Contact surfaces for electrical and electronic components

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TECHNICAL SPECIFICATIONS

Electrolyte characteristics	
Electrolyte type	alkaline-cyanide
Metal content	100 g/l Ag
pH value	12.5
Operating temperature	30 - 75 °C (optimum 35 °C)
Current density	10 - 150 A/dm²
Plating speed	0.2 - 1.5 µm/s
Anode material	Fine silver or MMO (type PLATINODE® 167 or 177)
Electric conductivity	>50 m*(Ω*mm²)$^{-1}$

Coating characteristics	
Coating	Fine silver
Purity	99.9 wt.% Ag
Colour of deposit	White
Brilliance	Semi-bright
Hardness of deposit HV 0.015 (Vickers) approx. values	110 HV (as plated)
Max. coating thickness	100 µm

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